

[Signature]**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: SHIBATA et al

Serial No.: 10/797,003

Filed: March 11, 2004

For: Mold Die And Method For Manufacturing Semiconductor
Device Using The Same

Art Unit:

Examiner:

AMENDMENTMail Stop: Amendment (No Fee)
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 13, 2004

Sir:

The following amendments and remarks are respectfully requested in connection with the above-identified application as listed below and as set forth on the following pages:

Amendments to the Specification;

Amendments to the Claims;

Amendments to the Abstract;

Remarks are included following the amendments.